# **Quad 2-Input AND Gate**

#### **General Description**

The VHC08 is an advanced high speed CMOS 2 Input AND Gate fabricated with silicon gate CMOS technology. It achieves the high-speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

The internal circuit is composed of 4 stages including buffer output, which provide high noise immunity and stable output. An input protection circuit insures that 0 V to 7 V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5 V to 3 V systems and two supply systems such as battery backup. This circuit prevents device destruction due to mismatched supply and input voltages.

#### **Features**

- High Speed:  $t_{PD} = 4.3$  ns (Typ.) at  $T_A = 25$ °C
- High Noise Immunity:  $V_{NIH} = V_{NIL} = 28\% \ V_{CC}$  (Min.)
- Power Down Protection is Provided on All Inputs
- Low Power Dissipation:  $I_{CC} = 2 \mu A \text{ (Max.)} @ T_A = 25^{\circ}C$
- Low Noise: V<sub>OLP</sub>= 0.8 V (Max.)
- Pin and Function Compatible with 74HC08



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MARKING DIAGRAMS

Order Number: 74VHC08M



SOIC14 CASE 751EF



= Assembly Location

WL = Wafer Lot Y = Year WW = Work Week

Order Number: 74VHC08MTCX



TSSOP-14 WB CASE 948G 14 ####### AXYKK V08 O

A = Assembly Location XY = 2-digit 2 Weekly Date Code KK = 2-digit Lot Run Code

Order Number: 74VHC08SJX

SOP14 CASE 565BE



A = Assembly Location
XY = 2-digit 2 Weekly Date Code
KK = 2-digit Lot Run Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

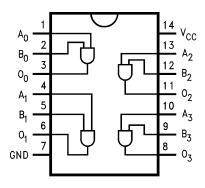


Figure 1. Connection Diagram

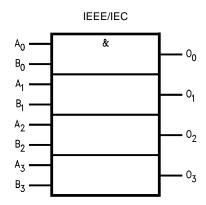


Figure 2. Logic Symbol

# **PIN DESCRIPTION**

Pin Names	Description
A <sub>n</sub> , B <sub>n</sub>	Inputs
O <sub>n</sub>	Outputs

#### **TRUTH TABLE**

Α	В	0
L	L	L
L	Н	L
Н	L	L
Н	Н	Н

# **ORDERING INFORMATION**

Part Number	Package Number	Package	Packing Method <sup>†</sup>
74VHC08M	M14A	SOIC14 (Pb-Free)	55 / Tube
74VHC08SJ	M14D	SOP14 (Pb-Free)	2000 / Tape & Reel
74VHC08MTC	MTC14	TSSOP-14 WB (Pb-Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	–0.5 V to +7.0 V
V <sub>IN</sub>	DC Input Voltage	–0.5 V to +7.0 V
V <sub>OUT</sub>	DC Output Voltage	–0.5 V to V <sub>CC</sub> + 0.5 V
I <sub>IK</sub>	Input Diode Current	–20 mA
I <sub>OK</sub>	Output Diode Current	±20 mA
lout	DC Output Current	±25 mA
I <sub>CC</sub>	DC V <sub>CC</sub> / GND Current	±50 mA
T <sub>STG</sub>	Storage Temperature	−65°C to +150°C
TL	Lead Temperature (Soldering, 10 seconds)	260°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# **RECOMMENDED OPERATING CONDITIONS** (Note 1)

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	2.0 V to +5.5 V
V <sub>IN</sub>	Input Voltage	0 V to +5.5 V
V <sub>OUT</sub>	Output Voltage	0 V to V <sub>CC</sub>
T <sub>OPR</sub>	Operating Temperature	−40°C to +85°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 ns/V ~ 100 ns/V 0 ns/V ~ 20 ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

<sup>1.</sup> Unused inputs must be held HIGH or LOW. They may not float.

# DC ELECTRICAL CHARACTERISTICS

						T <sub>A</sub> = 25°	C	T <sub>A</sub> = -40°0	C to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Con	ditions	Min	Тур	Max	Min	Max	Units
V <sub>IH</sub>	HIGH Level Input	2.0			1.50			1.50		V
	Voltage	3.0-5.5			0.7 x V <sub>CC</sub>			0.7 x V <sub>CC</sub>		
V <sub>IL</sub>	LOW Level Input	2.0					0.50		0.50	V
	Voltage	3.0-5.5					0.3 x V <sub>CC</sub>		0.3 x V <sub>CC</sub>	
V <sub>OH</sub>	HIGH Level Output	2.0		I <sub>OH</sub> = -50 μA	1.9	2.0		1.9		V
	Voltage	3.0	or V <sub>IL</sub>		2.9	3.0		2.9		
		4.5	]		4.4	4.5		4.4		
		3.0		I <sub>OH</sub> = -4 mA	2.58			2.48		
		4.5		I <sub>OH</sub> = -8 mA	3.94			3.80		
V <sub>OL</sub>	LOW Level Output	2.0	$V_{IN} = V_{IH}$	I <sub>OL</sub> = 50 μA		0.0	0.1		0.1	V
	Voltage	3.0	or V <sub>IL</sub>			0.0	0.1		0.1	
		4.5				0.0	0.1		0.1	
		3.0		I <sub>OL</sub> =4 mA			0.36		0.44	
		4.5		I <sub>OL</sub> =8 mA			0.36		0.44	
I <sub>IN</sub>	Input Leakage Current	0–5.5	V <sub>IN</sub> = 5.5	V or GND			±0.1		±1.0	μΑ
lcc	Quiescent Supply Current	5.5	V <sub>IN</sub> = V	<sub>CC</sub> or GND			2.0		20.0	μΑ

# **NOISE CHARACTERISTICS**

				<b>T</b> <sub>A</sub> =	25°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Тур	Limits	Units
V <sub>OLP</sub> <sup>(2)</sup>	Quiet Output Maximum Dynamic V <sub>OL</sub>	5.0	C <sub>L</sub> = 50 pF	0.3	0.8	V
V <sub>OLV</sub> <sup>(2)</sup>	Quiet Output Minimum Dynamic V <sub>OL</sub>	5.0	C <sub>L</sub> = 50 pF	-0.3	-0.8	V
V <sub>IHD</sub> <sup>(2)</sup>	Minimum HIGH Level Dynamic Input Voltage	5.0	C <sub>L</sub> = 50 pF		3.5	V
V <sub>ILD</sub> <sup>(2)</sup>	Maximum LOW Level Dynamic Input Voltage	5.0	C <sub>L</sub> = 50 pF		1.5	V

<sup>2.</sup> Parameter guaranteed by design.

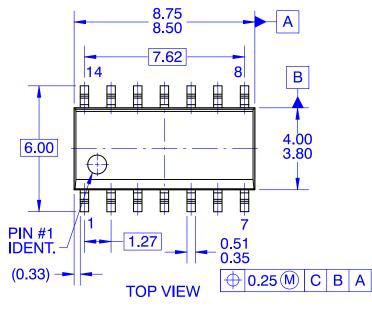
# **AC ELECTRICAL CHARACTERISTICS**

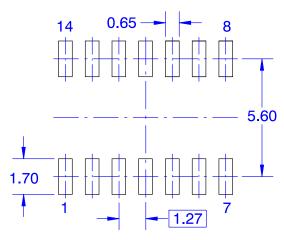
					T <sub>A</sub> = 25°C	;	T <sub>A</sub> = -40°0	C to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Units
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation Delay	$3.3 \pm 0.3$	C <sub>L</sub> = 15 pF		6.2	8.8	1.0	10.5	ns
			C <sub>L</sub> = 50 pF		8.7	12.3	1.0	14.0	
		5.0 ± 0.5	C <sub>L</sub> = 15 pF		4.3	5.9	1.0	7.0	ns
			C <sub>L</sub> = 50 pF		5.8	7.9	1.0	9.0	
C <sub>IN</sub>	Input Capacitance		V <sub>CC</sub> = Open		4	10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance		(Note 3)		18				pF

<sup>3.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC</sub> (opr.) = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>IN</sub> + I<sub>CC</sub> / 4 (per gate).

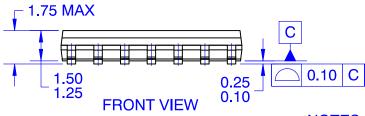


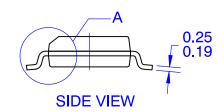
**DATE 30 SEP 2016** 





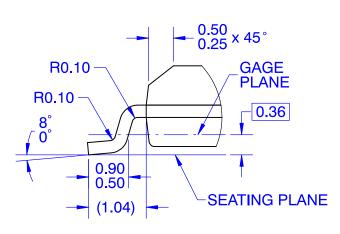
LAND PATTERN RECOMMENDATION





# **NOTES:**

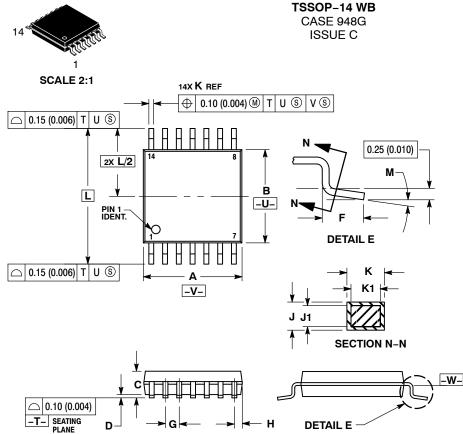
- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
  B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- LAND PATTERN STANDARD: SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009



DETAIL A SCALE 16:1

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**DATE 17 FEB 2016** 

- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

  6. TERMINAL NUMBERS ARE SHOWN FOR DEFERENCE ONLY
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	BSC	0.252	BSC	
М	o°	8 °	0 °	8 °	

#### **GENERIC MARKING DIAGRAM\***



= Assembly Location

= Wafer Lot V = Year

W = Work Week

= Pb-Free Package (Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

SOLDERIN	G FOOTPRINT
-	7.06
1	
— <u>—</u>	
, <u></u>	PITCH
14X 0.36	<del></del>
1.26	DIMENSIONS: MILLIMETERS

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